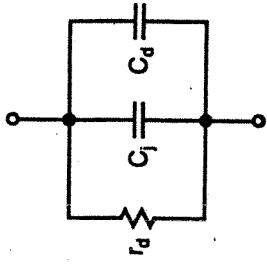


$C_j = \frac{C_{j0}}{\sqrt{1 + \frac{V_R}{\Phi_0}}}$	$Q = 2C_{j0}\Phi_0 \sqrt{1 + \frac{V_R}{\Phi_0}}$
$C_{j0} = \sqrt{\frac{qK_s \epsilon_0 N_D N_A}{2\Phi_0 (N_A + N_D)}}$	$C_{j0} = \sqrt{\frac{qK_s \epsilon_0 N_D}{2\Phi_0}}$ if $N_A \gg N_D$
$\Phi_0 = \frac{kT}{q} \ln \left(\frac{N_A N_D}{n_i^2} \right)$	

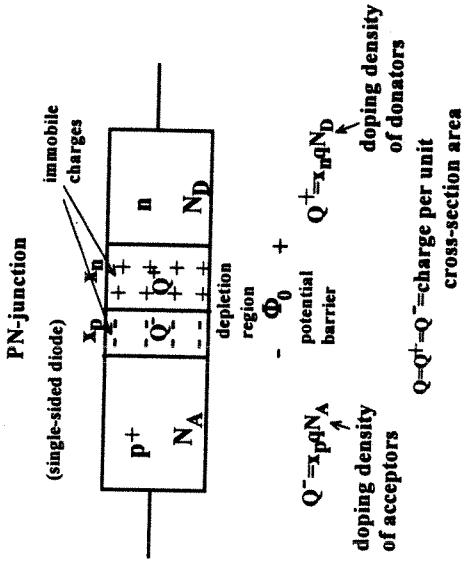
Forward-Biased Diode

$I_D = I_S e^{V_D V_T}$	$I_S = A_D q n_i^2 \left(\frac{D_n}{L_n N_A} + \frac{D_p}{L_p N_D} \right)$
$V_T = \frac{kT}{q} \equiv 26 \text{ mV at } 300 \text{ }^\circ\text{K}$	



$r_d = \frac{V_T}{I_D}$	$C_T = C_d + C_j$
$C_d = \tau_T \frac{I_D}{V_T}$	$C_j \equiv 2C_{j0}$
$\tau_T = \frac{L_n^2}{D_n}$	

τ_T = transit time for diode



C_j = diode depletion capacitance Φ_0 = built-in voltage PN-junction

N_D = doping concentration
electrons N_A = doping concentration
holes

I_S = scale current V_T = thermal voltage

D_n = diffusion constant
of electrons, p-side D_p = diffusion constant
of holes, n-side

L_n = diffusion length
of electrons, p-side L_p = diffusion length
of holes, n-side

$Q^- = qN_A$
doping density
of acceptors $Q^+ = qN_D$
doping density
of donors

$Q^- = qN_A$
charge per unit
cross-section area

Table 1.1 Important SPICE parameters for modelling diodes

SPICE Parameter	Model Constant	Brief Description	Typical Value
IS	I _s	Transport saturation current	10 ⁻¹⁷ A
RS	R _d	Series resistance	30 Ω
TT	τ _T	Diode transit time	12 ps
CJ	C ₁₀	Capacitance at 0-V bias	0.01 pF
MJ	m _i	Diode grading coefficient exponent	0.5
PB	Φ ₀	Built-in diode contact potential	0.9 V

q = 1.602 × 10 ⁻¹⁹ C	K = 1.38 × 10 ⁻²³ JK ⁻¹
n _i = 1.1 × 10 ¹⁶ carriers/m ³ at T = 300 °K	ε ₀ = 8.854 × 10 ⁻¹² F/m
K _{ox} ≡ 3.9	K _s ≡ 11.8
μ _n = 0.05 m ² /V · s	μ _p = 0.02 m ² /V · s

k = Boltzmann's constant

ε₀ = permittivity
for free space

n_i = carrier concentration
intrinsic silicon

K_{ox} = relative permittivity for SiO₂ K_s = relative permittivity for Siμ_n = mobility of electronsμ_p = mobility of holes

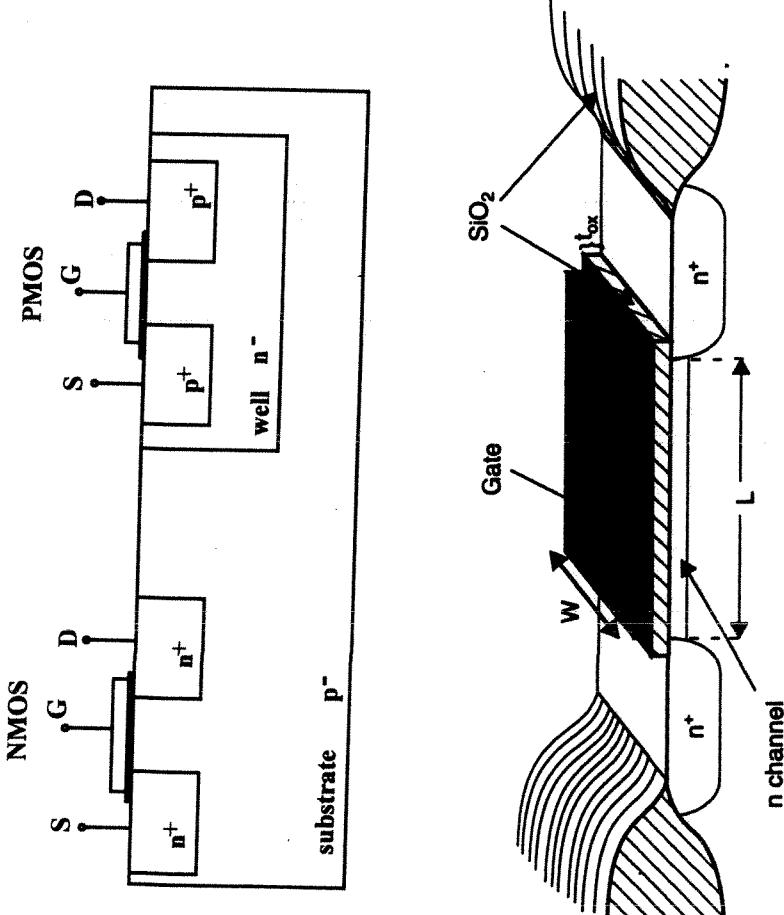


Fig. 1.10 The important dimensions of a MOS transistor.

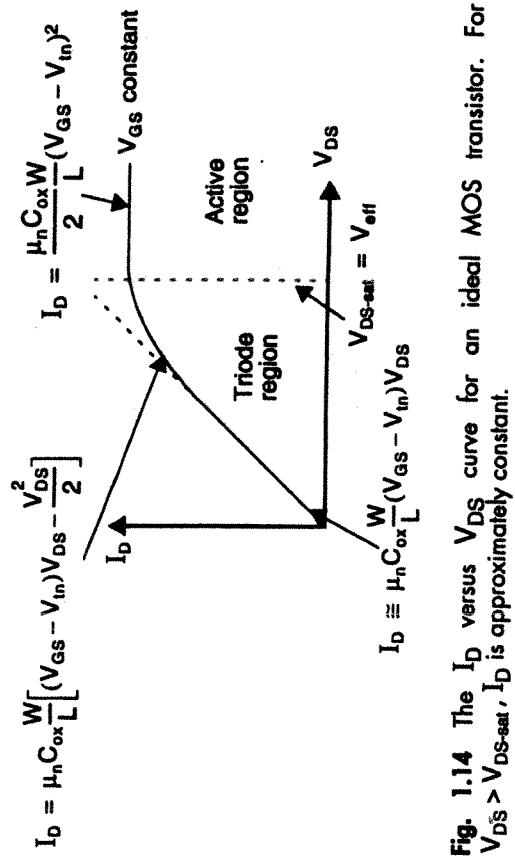


Fig. 1.14 The I_D versus V_{DS} curve for an ideal MOS transistor. For $V_{DS} > V_{DS\text{-sat}}$, I_D is approximately constant.

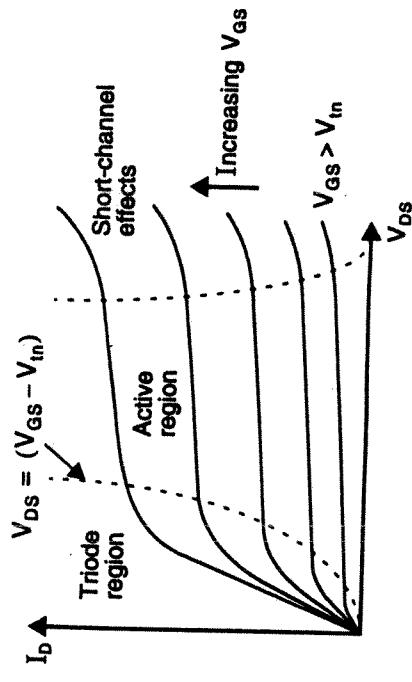


Fig. 1.16 I_D versus V_{DS} for different values of V_{GS} .

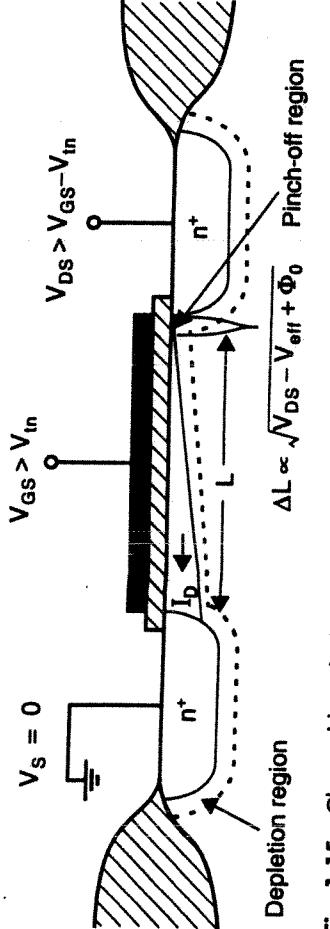


Fig. 1.15 Channel length shortening for $V_{DS} > V_{eff}$.

$$V_{tn} = \text{threshold voltage n-channel}$$

The following equations are for n-channel devices—for p-channel devices, put negative signs in front of all voltages. These equations do not account for short-channel effects (i.e., $L < 2L_{min}$).

Triode Region ($V_{GS} > V_{tn}$, $V_{DS} \leq V_{eff}$)

$I_D = \mu_n C_{ox} \left(\frac{W}{L} \right) \left[(V_{GS} - V_{tn}) V_{DS} - \frac{V_{DS}^2}{2} \right]$
$V_{eff} = V_{GS} - V_{tn}$ $V_{tn} = V_{tn-0} + \gamma \sqrt{V_{SB} + 2\phi_F - \sqrt{2\phi_F}}$

C_{ox} = gate capacitance t_{ox} = thickness of insulating SiO_2

W = gate width L = effective gate length

Φ_F = Fermi potential γ = body-effect constant

λ = output impedance [V^{-1}]

V_{tp} = threshold voltage p-channel (negative)

C_{S-SW} = capacitance between source and sidewalls

C_{D-SW} = capacitance between drain and sidewalls

N_B = doping concentration bulk

Active (or Pinch-Off) Region ($V_{GS} > V_{tn}$, $V_{DS} \geq V_{eff}$)

$I_D = \frac{\mu_n C_{ox} W}{2} \frac{1}{L} (V_{GS} - V_{tn})^2 [1 + \lambda(V_{DS} - V_{eff})]$
$\lambda \propto \frac{1}{L \sqrt{V_{DS} - V_{eff} + \Phi_0}}$ $V_{tn} = V_{tn-0} + \gamma \sqrt{V_{SB} + 2\phi_F - \sqrt{2\phi_F}}$
$V_{eff} = V_{GS} - V_{tn} = \sqrt{\frac{2I_D}{\mu_n C_{ox} W / L}}$

$\Phi_F = \frac{kT}{q} \ln \left(\frac{N_A}{n_i} \right)$	$\gamma = \frac{\sqrt{2qK_s \epsilon_0 N_A}}{C_{ox}}$
$C_{ox} = \frac{K_{ox} \epsilon_0}{t_{ox}}$	

Table 1.2 A reasonable set of MOS parameters for a typical 0.8- μm technology

SPICE Parameter	Model Constant	Brief Description	Typical Value
VTO	$V_{tn}:V_{tp}$	Transistor threshold voltage (in V)	0.7:-0.9
UO	$\mu_n:\mu_p$	Carrier mobility in bulk (in $\text{cm}^2/\text{V}\cdot\text{s}$)	500:175
TOX	t_{ox}	Thickness of gate oxide (in m)	1.8×10^{-8}
LD	L_D	Lateral diffusion of junction under gate (in m)	6×10^{-8}
GAMMA	γ	Body-effect parameter	0.5: 0.8
NSUB	$N_A:N_D$	The substrate doping (in cm^{-3})	$3 \times 10^{16}:7.5 \times 10^{16}$
PHI	$ 2\phi_F $	Surface inversion potential (in V)	0.7
PB	Φ_0	Built-in contact potential of junction to bulk (in V)	0.9
CJ	C_{j0}	Junction-depletion capacitance at 0-V bias (in F/m^2)	$2.5 \times 10^{-4}:4.0 \times 10^{-4}$
CJSW	C_{j-sw0}	Sidewall capacitance at 0-V bias (in F/m)	$2.0 \times 10^{-10}:2.8 \times 10^{-10}$
MJ	m_j	Bulk-to-junction exponent (grading coefficient)	0.5
MJSW	m_{j-sw}	Sidewall-to-junction exponent (grading coefficient)	0.3

Typical Values for a 0.8- μm Process

$V_{tn} = 0.8 \text{ V}$	$V_{tp} = -0.9 \text{ V}$
$\mu_n C_{ox} = 90 \text{ } \mu\text{A/V}^2$	$\mu_p C_{ox} = 30 \text{ } \mu\text{A/V}^2$

$C_{ox} = 1.9 \times 10^{-3} \text{ pF}/(\mu\text{m})^2$	$C_j = 2.4 \times 10^{-4} \text{ pF}/(\mu\text{m})^2$
$C_{j-sw} = 2.0 \times 10^{-4} \text{ pF}/\mu\text{m}$	$C_{gs(overlap)} = 2.0 \times 10^{-4} \text{ pF}/\mu\text{m}$
$\phi_F = 0.34 \text{ V}$	$\Phi_0 = 0.9 \text{ V}$
$\gamma = 0.5 \text{ V}^{1/2}$	$t_{ox} = 0.02 \text{ } \mu\text{m}$
$N_B = 6 \times 10^{21} \text{ impurities/m}^3$	

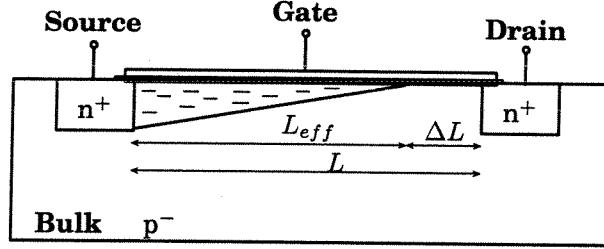
Derivation. RELATION BETWEEN I_D AND V_{DS} WHEN CHANNEL LENGTH MODULATION

At *pinch-off* limit:

$$I_{D,sat} = \frac{\mu_n C_{ox}}{2} \left(\frac{W}{L} \right) (V_{GS} - V_{tn})^2 \quad (1)$$

When $V_{DS} > V_{DS,sat}$:

$$I_D = \frac{\mu_n C_{ox}}{2} \left(\frac{W}{L_{eff}} \right) (V_{GS} - V_{tn})^2 \quad (2)$$



Assumptions: $V_{GS} > V_{tn}$, $V_{DS} > V_{GS} - V_{tn} = V_{eff}$. $N_D \gg N_A \Rightarrow \Delta L = x_p + x_n \approx x_p$.

$$L_{eff} = L - \Delta L \quad (3)$$

$$\begin{aligned} \Delta L \approx x_p &= \frac{Q_-}{q \cdot N_A} = \frac{1}{q \cdot N_A} \sqrt{2qK_s\epsilon_0(\phi_0 + V_R) \frac{N_A N_D}{N_A + N_D}} = \sqrt{\frac{2K_s\epsilon_0(\phi_0 + V_R)}{q} \cdot \frac{N_D}{N_A(N_A + N_D)}} \\ &\approx \sqrt{\frac{2K_s\epsilon_0(\phi_0 + V_R)}{q} \cdot \frac{1}{N_A}} = k_{ds} \sqrt{V_R + \phi_0} = k_{ds} \sqrt{V_{DS} - V_{eff} + \phi_0} \end{aligned} \quad (4)$$

$$k_{ds} = \sqrt{\frac{2K_s\epsilon_0}{qN_A}} \quad V_R = V_{DS} - V_{DS,sat} = V_{DS} - V_{eff} \quad V_{eff} = V_{GS} - V_{tn}$$

- V_{DS} increase $\Rightarrow \Delta L$ increase $\Rightarrow L_{eff}$ decrease $\Rightarrow I_D$ increase.

- Determine the relation between I_D and V_{DS} !

$$(2) \Rightarrow I_D = \frac{A}{L_{eff}} (V_{GS} - V_{tn})^2 \quad (5)$$

$$(1) \Rightarrow I_{D,sat} = \frac{A}{L} (V_{GS} - V_{tn})^2 \quad (6)$$

Taylorseries around $I_{D,sat}$:

$$I_D = I_{D,sat} + \left. \frac{\partial I_D}{\partial L_{eff}} \right|_{L_{eff}=L} \cdot \left. \frac{\partial L_{eff}}{\partial V_{DS}} \right|_{V_{DS}=V_{DS,sat}} \cdot \Delta V_{DS} \quad (7)$$

Derivating (5) and (3) gives:

$$\begin{aligned}\frac{\partial I_D}{\partial L_{eff}} &= -\frac{A}{L_{eff}^2} (V_{GS} - V_{tn})^2 \\ \frac{\partial L_{eff}}{\partial V_{DS}} &= \frac{\partial(L - \Delta L)}{\partial V_{DS}} = -\frac{\partial \Delta L}{\partial V_{DS}} = -\frac{k_{ds}}{2} \frac{1}{\sqrt{V_{DS} - V_{eff} + \phi_0}} \\ \Delta V_{DS} &= V_{DS} - V_{DS,sat} = V_{DS} - V_{eff}\end{aligned}\quad (8)$$

(6), (7) and (8) give:

$$\begin{aligned}I_D &= \frac{A}{L} (V_{GS} - V_{tn})^2 + \left(-\frac{A}{L^2} (V_{GS} - V_{tn})^2 \right) \left(-\frac{k_{ds}}{2} \frac{1}{\sqrt{V_{DS,sat} - V_{eff} + \phi_0}} \right) (V_{DS} - V_{eff}) \\ &= \frac{A}{L} (V_{GS} - V_{tn})^2 \left(1 + \frac{k_{ds}}{2L} \cdot \frac{1}{\sqrt{\phi_0}} \cdot (V_{DS} - V_{eff}) \right) \\ &= \frac{\mu_n C_{ox}}{2} \left(\frac{W}{L} \right) (V_{GS} - V_{tn})^2 (1 + \lambda(V_{DS} - V_{eff})) \\ &= \alpha \cdot V_{eff}^2 (1 + \lambda(V_{DS} - V_{eff}))\end{aligned}$$

I.e.:

$$I_D = \alpha \cdot V_{eff}^2 (1 + \lambda(V_{DS} - V_{eff})) \quad (9)$$

where $\alpha = \frac{\mu_n C_{ox}}{2} \cdot \frac{W}{L}$ and channellength-modulation constant

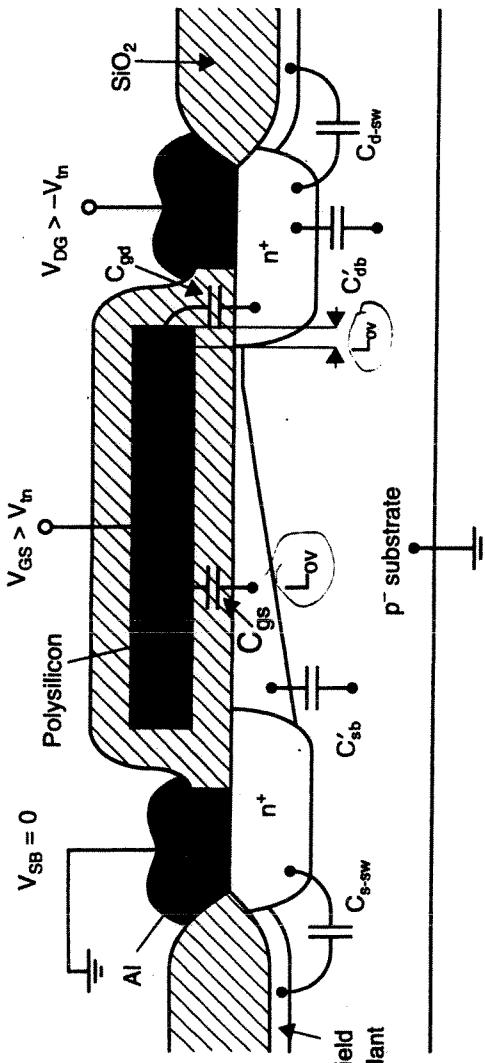
$$\lambda = \frac{k_{ds}}{2L \cdot \sqrt{\phi_0}} ; \quad k_{ds} = \sqrt{\frac{2K_s \epsilon_0}{qN_A}}$$

Matching

Differentiate the saturation current

$$I_D = K' \frac{W}{L} (V_{GS} - V_T)^2 (1 + \lambda V_{DS}) \text{ this gives}$$

$$\frac{\Delta I_D}{I_D} = \frac{\Delta K'}{K'} + \frac{\Delta W}{W} - \frac{\Delta L}{L} + 2 \frac{\Delta V_{GS} - \Delta V_T}{V_{GS} - V_T} + \frac{\Delta V_{DS} \lambda + V_{DS} \lambda}{1 + \lambda V_{DS}}$$



1.20 A cross section of an n-channel MOS transistor showing the small-signal capacitances.

Rule of thumb 1

$V_{GS} - V_T = V_{eff} > 0.15\text{--}0.25$ to obtain good V_T -matching.

Rule of thumb 2

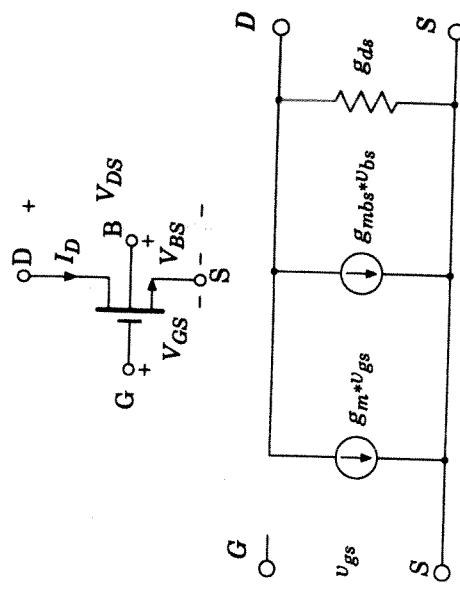
Choose $L \geq 1.5L_{min}$ for good β -matching.
Choose $W \gg W_{min}$ for high gain and good β -matching.

Table 1.2 A reasonable set of MOS parameters for a typical 0.8-μm technology

SPICE Parameter	Model Constant	Brief Description	Typical Value
VTO	$V_{in}; V_{tp}$	Transistor threshold voltage (in V)	0.7:−0.9
UO	$\mu_n; \mu_p$	Carrier mobility in bulk (in $\text{cm}^2/\text{V}\cdot\text{s}$)	500:175
TOX	t_{ox}	Thickness of gate oxide (in nm)	1.8×10^{-4}
LD	L_D	Lateral diffusion of junction under gate (in nm)	6×10^{-4}
GAMMA	γ	Body-effect parameter	0.5:0.8
NSUB	$N_A; N_D$	The substrate doping (in cm^{-3})	$3 \times 10^{16}; 7.5 \times 10^{16}$
PHI	$ \Phi $	Surface inversion potential (in V)	0.7
PB	Φ_0	Built-in contact potential of junction to bulk (in V)	0.9
CJ	C_{j0}	Junction-depletion capacitance at 0-V bias (in F/m^2)	$2.5 \times 10^{-4}; 4.0 \times 10^{-4}$
CJSW	$C_{j,sw}$	Side-wall capacitance at 0-V bias (in F/m)	$2.0 \times 10^{-10}; 2.8 \times 10^{-10}$
MJ	m_1	Bulk-to-junction exponent (grading coefficient)	0.5
MJSW	$m_{j,sw}$	Side-wall-to-junction exponent (grading coefficient)	0.3

Small-signal model (Linear region)

$$I_D = \beta \left[(V_{GS} - V_T)V_{DS} - \frac{V_{DS}^2}{2} \right]$$

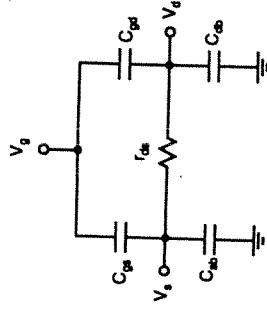


$$g_{ds} = \frac{\partial I_D}{\partial V_{DS}} = \beta [V_{GS} - V_T - V_{DS}]$$

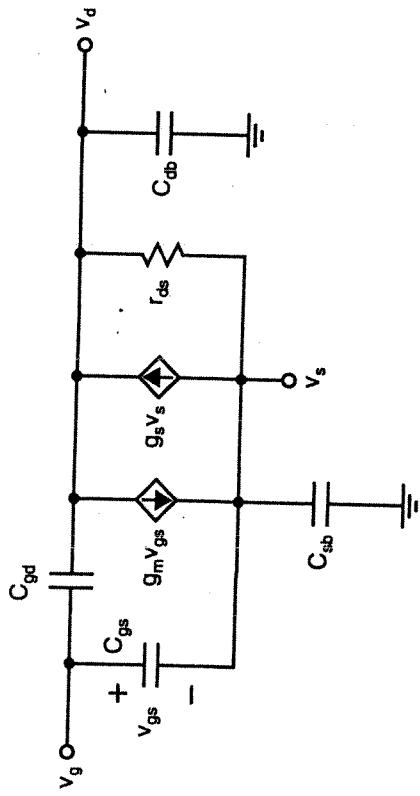
$$g_m = \frac{\partial I_D}{\partial V_{GS}} = \beta V_{DS} \approx 0$$

$$g_{mbs} = \frac{\partial I_D}{\partial V_{BS}} = \eta g_m \approx 0$$

Small-Signal Model in Triode Region (for $V_{DS} \ll V_{eff}$)



$C_{gd} = C_{gs} \equiv \frac{1}{2}WL_C_{ox} + Wl_{ov}C_{ox}$	$r_{ds} = \frac{1}{H_n C_{ox} \left(\frac{W}{L} \right) V_{eff}}$	$C_{sb} = C_{db} = \frac{C_{pb}(A_s + WL/2)}{\sqrt{1 + \frac{V_{ab}}{\Phi_0}}}$
---------------------------------------------------------------	--------------------------------------------------------------------	---------------------------------------------------------------------------------



$$g_m = \mu_n C_{ox} \left(\frac{W}{L} \right) V_{eff}$$

$$g_s = \frac{\gamma g_m}{2\sqrt{V_{SB} + |2\phi_F|}}$$

$$g_{ds} \equiv 0.2 g_m$$

$$\lambda = \frac{k_{rds}}{2L\sqrt{V_{DS} - V_{eff} + \Phi_0}}$$

$$k_{rds} = \frac{2K_s \varepsilon_0}{qN_A}$$

$$C_{gs} = \frac{2}{3}WL_C_{ox} + WL_{ov}C_{ox}$$

$$C_{gd} = WL_{ov}C_{ox}$$

$$C_{js} = \frac{C_{j0}}{\sqrt{1 + V_{SB}/\Phi_0}}$$

$$C_{jd} = \frac{C_{j0}}{\sqrt{1 + V_{DB}/\Phi_0}}$$

$$C_{db} = A_d C_{jd} + P_d C_{j-sw}$$

$$C_{gb} = C_{gs} \equiv \frac{1}{2}WL_C_{ox} + Wl_{ov}C_{ox}$$

$$C_{gb} = C_{gs} \equiv \frac{1}{2}WL_C_{ox} + Wl_{ov}C_{ox}$$

$$C_{gb} = C_{gs} \equiv \frac{1}{2}WL_C_{ox} + Wl_{ov}C_{ox}$$

Small-Signal Model (Active Region)

DETERMINE g_m AND g_{ds}

$$g_m = \frac{2I_{DQ}}{V_{GSQ} - V_t} \quad g_{ds} = \frac{1}{r_{ds}} = \lambda I_{DQ} \quad \frac{g_m}{g_{ds}} = \frac{2}{\lambda(V_{GSQ} - V_t)}$$

Regard a 0.35 μm CMOS-process ($L_{\min} = 0.35 \mu\text{m}$):

	NMOS $L=1 \mu\text{m}$	PMOS $L=1 \mu\text{m}$	
λ	0.03	0.05	[1/V]
V_t	0.47	0.62	[V]
μ	400	130	[cm ² /Vs]
C_{ox}	$4.5 \cdot 10^{-7}$	$4.5 \cdot 10^{-7}$	[F/cm ²]

For good matching choose $V_{GSQ} - V_t$ in the interval [0.15,0.25] V.

Choose e.g.. $V_{GSQ} - V_t = 0.25$ V

$$\text{NMOS: } \frac{g_m}{g_{ds}} = \frac{2}{0.03 \cdot 0.25} \approx 267$$

$$\text{PMOS: } \frac{g_m}{g_{ds}} = \frac{2}{0.05 \cdot 0.25} = 160$$

Determine g_m : $g_m = \mu C_{ox} \frac{W}{L} (V_{GSQ} - V_t)$

Suppose: $W = 10 \mu\text{m}$, $L = 1 \mu\text{m}$ och $V_{GSQ} - V_t = 0.25$ V

$$\text{NMOS: } g_m = 400 \cdot 4.5 \cdot 10^{-7} \cdot 10 \cdot 0.25 = 0.45 \cdot 10^{-3} [\text{S}]$$

$$\text{PMOS: } g_m = 130 \cdot 4.5 \cdot 10^{-7} \cdot 10 \cdot 0.25 \approx 0.15 \cdot 10^{-3} [\text{S}]$$

Determine g_{ds} :

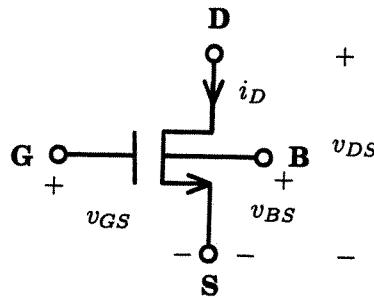
$$\text{NMOS: } g_{ds} = \frac{g_m}{267} \approx 1.69 \cdot 10^{-6} [\text{S}] \Rightarrow r_{ds} \approx 0.59 \text{ M}\Omega$$

$$\text{PMOS: } g_{ds} = \frac{g_m}{160} \approx 0.9 \cdot 10^{-6} [\text{S}] \Rightarrow r_{ds} \approx 1.09 \text{ M}\Omega$$

DERIVATION OF A SMALL SIGNAL EQUIVALENT FOR NMOS-TRANSISTOR

Regard i_D as a function of v_{GS} , v_{BS} and v_{DS} :

$$i_D = f(v_{GS}, v_{BS}, v_{DS}) \quad (1)$$



i_D , as well as v_{GS} , v_{BS} and v_{DS} consists of an DC-part, I_{DQ} , V_{GSQ} , V_{BSQ} and V_{DSQ} (the quiscent point) and an AC-part i_d , v_{gs} , v_{bs} and v_{ds} (the small signal).

$$i_D = I_{DQ} + i_d, v_{GS} = V_{GSQ} + v_{gs}, v_{BS} = V_{BSQ} + v_{bs}, v_{DS} = V_{DSQ} + v_{ds} \quad (2)$$

That is:

$$I_{DQ} + i_d = f(V_{GSQ} + v_{gs}, V_{BSQ} + v_{bs}, V_{DSQ} + v_{ds}) \quad (3)$$

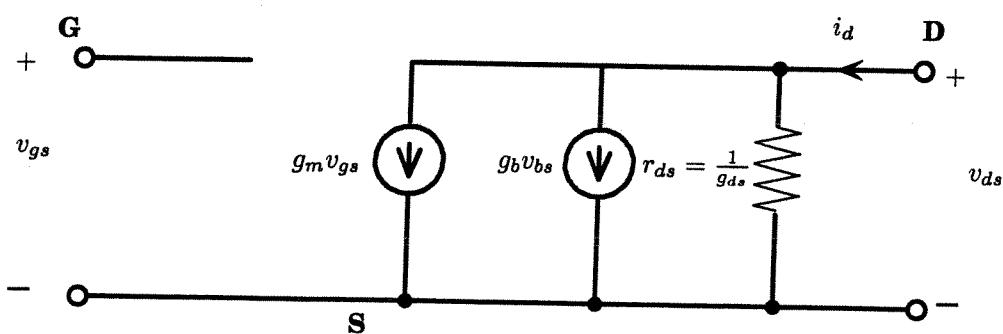
Taylor's formula for 3 variables gives:

$$I_{DQ} + i_d = \underbrace{f(V_{GSQ}, V_{BSQ}, V_{DSQ})}_{I_{DQ}} + \underbrace{\frac{\partial f}{\partial v_{GS}} \Big|_Q}_{g_m} \cdot v_{gs} + \underbrace{\frac{\partial f}{\partial v_{BS}} \Big|_Q}_{g_b} \cdot v_{bs} + \underbrace{\frac{\partial f}{\partial v_{DS}} \Big|_Q}_{g_{ds}} \cdot v_{ds} \quad (4)$$

That is:

$$i_d = g_m \cdot v_{gs} + g_b \cdot v_{bs} + g_{ds} \cdot v_{ds} \quad (5)$$

Equation (5) gives following equivalent small signal scheme:



To calculate the values of g_m , g_b and g_{ds} we first have to determine in which region the transistor is operating.

(CONT. \rightarrow)

We presume that the transistor operates in the SATURATION region, where following relations applies: (Notice that $v_{BS} = -v_{SB}$)

$$i_D = \alpha(v_{GS} - V_t)^2(1 + \lambda(v_{DS} - V_{eff})) \quad (6)$$

$$V_t = V_{t0} + \gamma \left(\sqrt{2|\phi_F| - v_{BS}} - \sqrt{2|\phi_F|} \right) \quad (7)$$

To determine g_m we derivate (6) with respect to v_{GS} :

$$\frac{\partial i_D}{\partial v_{GS}} = 2\alpha(v_{GS} - V_t)(1 + \lambda(v_{DS} - V_{eff}))$$

The value of this derivative in the Q-point gives g_m :

$$g_m = 2\alpha(V_{GSQ} - V_t)(1 + \lambda(V_{DSQ} - V_{eff})) = \frac{2I_{DQ}}{V_{GSQ} - V_t} \quad (8)$$

Neglecting the channel-length modulation gives the approximation:

$$g_m \approx 2\sqrt{\alpha I_{DQ}}$$

To determine g_{ds} we derivate (6) with respect to v_{DS} and calculate the value in the Q-point.

$$\frac{\partial i_D}{\partial v_{DS}} = \lambda \cdot \alpha(v_{GS} - V_t)^2$$

That is:

$$g_{ds} = \lambda \cdot \alpha(V_{GSQ} - V_t)^2 \approx \lambda I_{DQ} \quad (9)$$

To determine g_b we have to use the chain-rule for derivatives, as we don't explicit have i_D as a function of v_{BS} .

$$\frac{\partial i_D}{\partial v_{BS}} = \frac{\partial i_D}{\partial V_t} \cdot \frac{\partial V_t}{\partial v_{BS}} = -2\alpha(v_{gs} - V_t)(1 + \lambda(v_{DS} - V_{eff})) \cdot \left(-\frac{\gamma}{2} (2|\phi_F| - v_{BS})^{-1/2} \right)$$

That is:

$$g_b = -\underbrace{2\alpha(V_{GSQ} - V_t)(1 + \lambda(V_{DSQ} - V_{eff}))}_{g_m} \cdot \left(-\frac{\gamma}{2} (2|\phi_F| - V_{BSQ})^{-1/2} \right) = g_m \cdot \frac{\gamma}{2\sqrt{2|\phi_F| - V_{BSQ}}} = \eta \cdot g_m \quad (10)$$

Conclusion:

$$\begin{cases} g_m &= \frac{2I_{DQ}}{V_{GSQ} - V_t} &\approx 2\sqrt{\alpha I_{DQ}} &\alpha \sim \frac{W}{L}; &g_m \sim \sqrt{\frac{W}{L}} \\ g_{ds} &= \lambda \cdot \alpha(V_{GSQ} - V_t)^2 &\approx \lambda I_{DQ} &\lambda \sim \frac{1}{L}; &g_{ds} \sim \frac{1}{L} \\ g_b &= g_m \cdot \frac{\gamma}{2\sqrt{2|\phi_F| - V_{BSQ}}} &= \eta \cdot g_m &\eta \approx 0.2; &g_b \sim \sqrt{\frac{W}{L}} \end{cases}$$